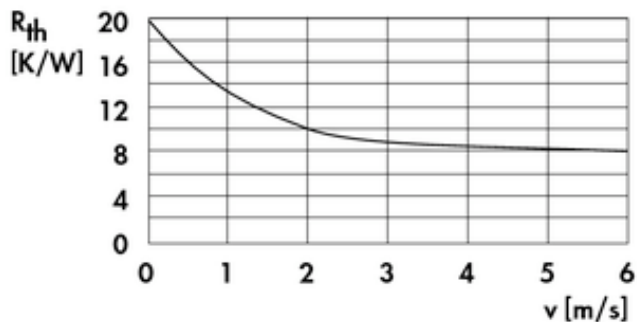
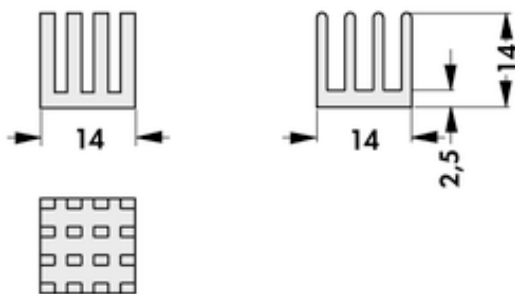
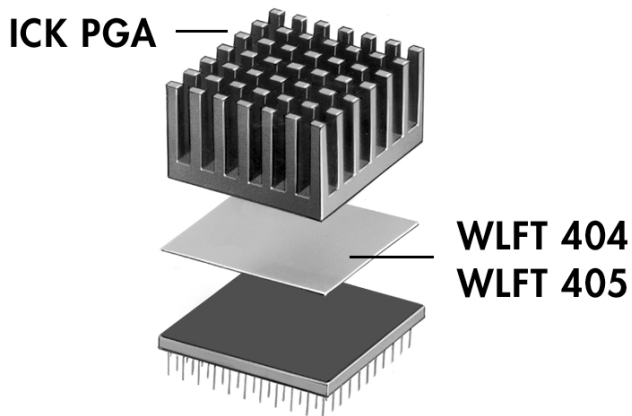


Heatsinks for PGA / **ICK PGA 6 x 6 x 14**



14 x 14 x 14 mm, for IC design PGA and others

Parameters of article ICK PGA 6 x 6 x 14

R_{th} [K/W]	18.6
dissipation loss [W]	6.4
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	14
height [mm]	14
plate thickness [mm]	2.5
length on stock [mm]	14
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 14 x 14**

Thermally conductive foil both sides adhesive / **WLFT 405 14 x 14**